

L Number	Hits	Search Text	DB	Time stamp
1	424	"front opening unified pod"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:35
2	0	"front open unified pod" and "front opening interface mechanical standards"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:30
3	1	"front open unified pod" and FIMS	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:31
4	70	"front open unified pod"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:32
5	6	"front open unified pod" and JIG	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:34
6	0	"front open unified pod" and JIG and purg\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:34
7	0	"front open unified pod" and JIG and gas	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:34
8	66	"front opening unified pod" and purg\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:35
9	59	"front opening unified pod" and purg\$4 and gas	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:37
10	12	"front opening unified pod" and purg\$4 and gas and gap	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/28 09:37
-	18890	(wafer or semiconductor or substrate) and JIG	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:36
-	264	(wafer or semiconductor or substrate) and JIG and purg\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:36
-	199	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:36
-	125	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas and atmosphere	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:36
-	19	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas and atmosphere and open\$4 and clos\$4 and door	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:44
-	1	(wafer or semiconductor or substrate) and JIG and purg\$4 and gas and atmosphere and open\$4 and clos\$4 and door and FIMS	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:55
-	151	(wafer or semiconductor or substrate) and FIMS	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:55

-	5	(wafer or semiconductor or substrate) and FIMS and JIG	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:55
-	5	(wafer or semiconductor or substrate) and FIMS and JIG and door and open\$4 and clos\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:56
-	1	(wafer or semiconductor or substrate) and FIMS and JIG and door and open\$4 and clos\$4 and purg\$4 and gas	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 10:56
-	2	(wafer or semiconductor or substrate) and FIMS and JIG and door and open\$4 and clos\$4 and gas	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 12:46
-	2	(purg\$3 adj gas) with door and JIG	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:00
-	1	(purg\$3 adj gas) with door and FIMS	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:01
-	71	(purg\$3 adj gas) with door	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:05
-	49	(purg\$3 adj gas) with door and (substrate or semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:06
-	41	(purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:06
-	14	(purg\$3 adj gas) with door and (substrate or semiconductor or wafer) and open\$4 and clos\$4 and gap	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:41
-	1844	(purg\$3 with gas) and (gas with (gap or door))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:42
-	1047	(purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:42
-	777	(purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:44
-	1	(purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig and fims	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:44
-	21	(purg\$3 with gas) and (gas with (gap or door)) and (wafer or semiconductor or substrate) and open\$4 and clos\$4 and jig	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/10/26 13:44